



Cleaner for Both Electroless and Electroplated Copper Surface

适用于化学铜与电镀铜的清洁剂

RONACLEAN™ EVP221 / 222S CLEANER

RONACLEAN™ EVP-221 cleaner is an acidic immersion type cleaner, has superior wetting ability and lower surface tension. It is effective in removing resist residues that may be left from incomplete development of dry film on an electroless or electroplated copper surface. RONACLEAN EVP-222S cleaner is an acidic sprayable product, developed for horizontal and new vertical-in-line plating equipment on IC Substrate and HDI PCB applications.

RONACLEAN EVP-221是浸泡式酸性清洁剂，能表现出优异的湿润效果，并有较低的表面张力。同时对于干膜工续后所残留的光阻，亦有良好的清洁效果; RONACLEAN EVP-222S一款喷洒型的酸性清洁剂产品，可搭配水平和新型垂直传动电镀设备生产IC基板和HDI板。

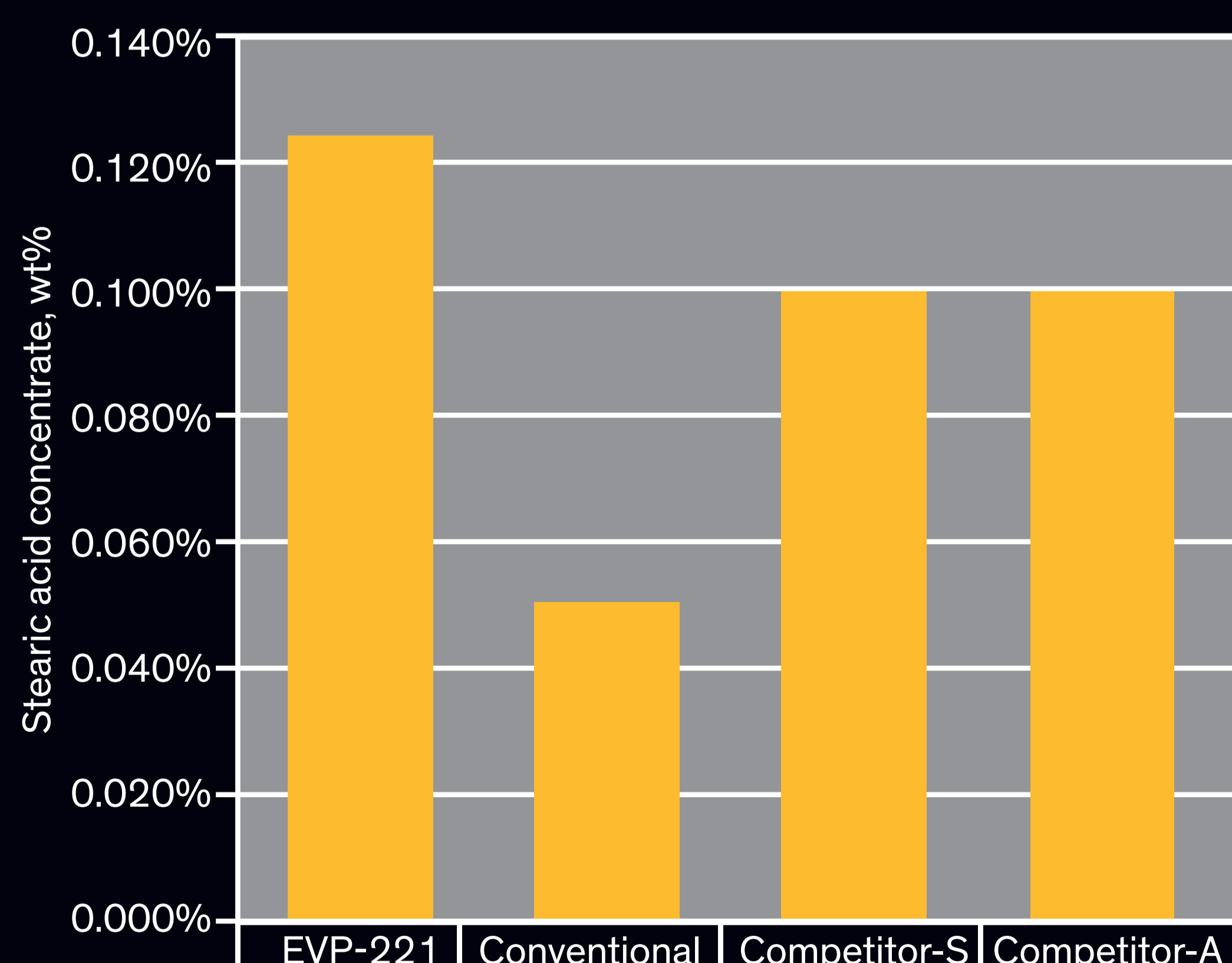
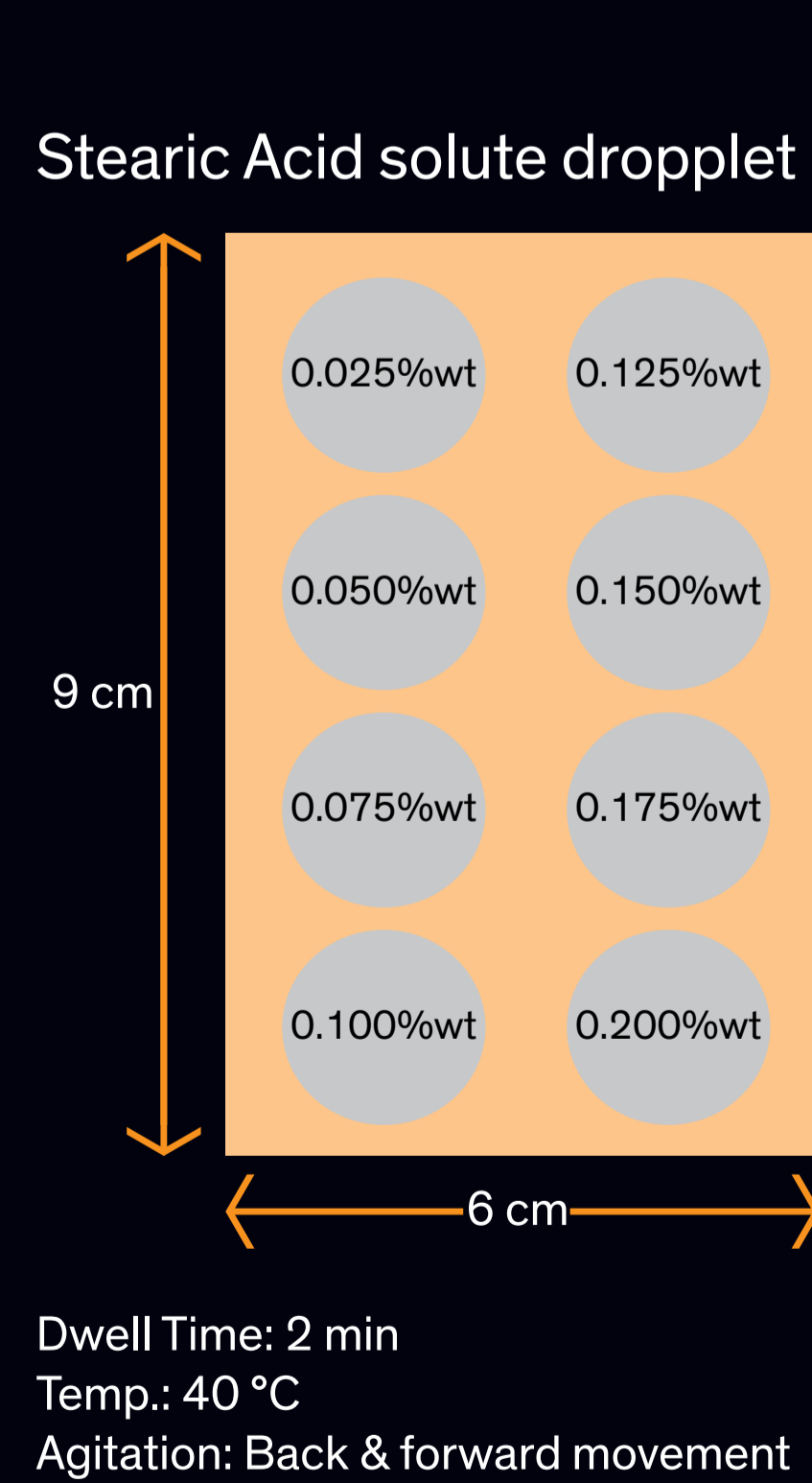
Advantage of RONACLEAN™ EVP 221/ 222S

RONACLEAN™ EVP 221/ 222S具备以下卓越的特性:

- Readily removes oils, light oxides and soils, improved rinsibility
易于去除油脂类，氧化物和脏污，清洗性能显著提升
- Contains neither Alkyl Phenol Ethoxylates (APE) nor strong chelating agent
不含烷基酚聚氧乙烯醚或强效螯合剂
- Low-foaming
少泡沫
- Ease of waste treatment
废水容易处理
- Good compatibility with Dow Electronic Materials acid copper electrolytes
与陶氏酸性铜电镀液有着良好的相容性

Detergency of EVP221

Remove stearic acid stain from cladmed copper surface



Panel after cleaner treatment:

Conventional Result

EVP221 Result

